BSIMProPlus

PRIMARIUS

Advanced SPICE Modeling Platform

Introduction

BSIMProPlus is industry's leading SPICE modeling platform for advanced semiconductor devices. As the technology and market leader for SPICE modeling, it has been adopted as the standard modeling tool in leading semiconductor companies worldwide for over a decade.

BSIMProPlus provides the most powerful SPICE modeling functions with its built-in parallel SPICE engine. BSIMProPlus offers full SPICE modeling capabilities from baseband to high frequency for various semiconductor devices for characterization, auto model extraction and parameter optimization in various technology nodes including 28nm, 14nm, 10nm, 7nm, 5nm and 3nm.

BSIMProPlus supports public domain SPICE models and popular proprietary models, and represents accurate and efficient SPICE modeling solution for process development and integrated circuit design.

Key Advantages

- Industry-Golden Platform
- Technology & market leader for SPICE modeling
- Wide Adoption
 Adopted by leading semiconductor companies worldwide
- One-Stop Solution

Meeting various baseband modeling requirements including electrical, physical, layout, etc.

- Full Coverage Covering various device types including compact models, user-defined models, etc.
- Applied in various processes including Planar, FinFET, GAA, etc.
- 3nm

GAA

- Applied in advanced process down to 7nm/5nm/3nm
- IGBT
- Supports power device modeling
- PRI

Supports reliability modeling such as PRI, Agemos, OMI, URI, MosRA, etc.

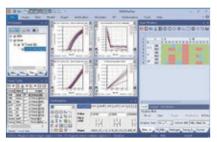
- RTN
- Supports RTN modeling

Application Examples

FinFET Device Model Extraction



Planar Device Model Extraction



compact Mode Mismatch Layout Statistical Effect Reliability Corner **BSIMProPlus** Best Noise Fitting Built-in Circuit NanoSpice Level OM

Specifications

Supports device types

- MOSFET, SOI, FinFET, BJT/HBT, TFT, MESFET, HEMT, Diode, Resistor, Inductor, etc

Supports models

- BSIM3, BSIM4, BSIM6, BSIM-CMG, BSIM-IMG, BSIMSOI, UTSOI, HiSIM2, HiSIM_HV, PSP, GP-BJT, RPI TFT, etc
- Continuously updated with the latest compact model versions such as BSIM4.8.1, BSIM-BULK 107.1, BSIM-CMG 111.21, BSIM IMG 103.0
- Supports latest model interface

- TMI, OMI and PMI

- Supports device characteristics
 - HSPICE/Spectre/Eldo compatible
 - Supports Device or circuit-level target modeling
 - Supports user-defined model and Verilog-A model
 - DC, AC, Tran, Noise, RF, Statistical, LDE, Reliability, etc
 - Supports model auto extraction and parameter optimization
 - Supports MPI and other mainstream probe stations for wafer-level semi-auto measurement
 - Supports mainstream instruments for DC/AC/RF/Reliability characterization

Applications

- SPICE modeling and model library development
- New device SPICE model development
- Semiconductor device data testing
- Reliability model development & validation

MOS Aging Model Extraction

